

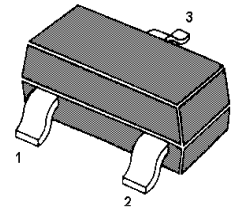
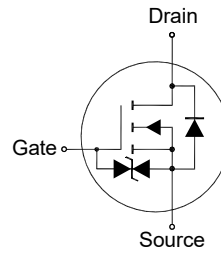
# MMFTN4003K

## N-Channel Enhancement Mode MOSFET

### Features

- Surface-mounted package
- Built-in G-S Protection Diode
- Typical ESD Protection HBM Class 2

Classification	Voltage Range(V)
0A	< 125
0B	125 to < 250
1A	250 to < 500
1B	500 to < 1000
1C	1000 to < 2000
2	2000 to < 4000
3A	4000 to < 8000
3B	≥ 8000



1. Gate 2. Source 3. Drain  
SOT-23 Plastic Package

### Application

- Portable appliances
- Battery management

### Absolute Maximum Ratings (at $T_a = 25^\circ\text{C}$ unless otherwise specified)

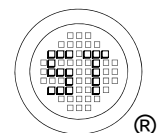
Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current	$I_D$	500	mA
Peak Drain Current, Pulsed <sup>1)</sup>	$I_{DM}$	1.7	A
Total Power Dissipation <sup>2)</sup>	$P_{tot}$	690	mW
Operating Junction and Storage Temperature Range	$T_j, T_{stg}$	- 55 to + 150	$^\circ\text{C}$

### Thermal Resistance Ratings

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient <sup>2)</sup>	$R_{\theta JA}$	181	$^\circ\text{C}/\text{W}$

<sup>1)</sup> Pulse Test: Pulse Width  $\leq 100 \mu\text{s}$ , Duty Cycle  $\leq 2\%$ , Repetitive rating, pulse width limited by junction temperature  $T_{j(\text{MAX})} = 150^\circ\text{C}$ .

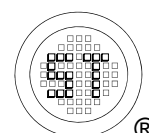
<sup>2)</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.



# MMFTN4003K

## Characteristics at $T_a = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit
<b>STATIC PARAMETERS</b>					
DrainSource Breakdown Voltage at $I_D = 100 \mu\text{A}$	$BV_{DSS}$	30	-	-	V
DrainSource Leakage Current at $V_{DS} = 30 \text{ V}$	$I_{DSS}$	-	-	1	$\mu\text{A}$
Gate Leakage Current at $V_{GS} = \pm 10 \text{ V}$	$I_{GSS}$	-	-	$\pm 1$	$\mu\text{A}$
GateSource Threshold Voltage at $V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	$V_{GS(th)}$	0.8	-	1.6	V
DrainSource OnState Resistance at $V_{GS} = 4.5 \text{ V}, I_D = 300 \text{ mA}$ at $V_{GS} = 2.5 \text{ V}, I_D = 100 \text{ mA}$	$R_{DS(on)}$	- -	- -	1.5 2.4	$\Omega$
<b>DYNAMIC PARAMETERS</b>					
Forward Transconductance at $V_{DS} = 10 \text{ V}, I_D = 115 \text{ mA}$	$g_{FS}$	-	270	-	mS
Input Capacitance at $V_{GS} = 0 \text{ V}, V_{DS} = 20 \text{ V}, f = 1 \text{ MHz}$	$C_{iss}$	-	37	-	pF
Output Capacitance at $V_{GS} = 0 \text{ V}, V_{DS} = 20 \text{ V}, f = 1 \text{ MHz}$	$C_{oss}$	-	11	-	pF
Reverse Transfer Capacitance at $V_{GS} = 0 \text{ V}, V_{DS} = 20 \text{ V}, f = 1 \text{ MHz}$	$C_{rss}$	-	9	-	pF
Gate charge total at $V_{DS} = 20 \text{ V}, I_D = 1 \text{ A}, V_{GS} = 10 \text{ V}$ at $V_{DS} = 20 \text{ V}, I_D = 1 \text{ A}, V_{GS} = 4.5 \text{ V}$	$Q_g$	- -	1.4 0.7	- -	nC
Gate to Source Charge at $V_{DS} = 20 \text{ V}, I_D = 1 \text{ A}, V_{GS} = 10 \text{ V}$	$Q_{gs}$	-	0.4	-	nC
Gate to Drain Charge at $V_{DS} = 20 \text{ V}, I_D = 1 \text{ A}, V_{GS} = 10 \text{ V}$	$Q_{gd}$	-	0.2	-	nC
Turn-On Delay Time at $I_D = 0.5 \text{ A}, V_{DD} = 20 \text{ V}, V_{GS} = 10 \text{ V}, R_G = 24 \Omega$	$t_{d(on)}$	-	6	-	ns
Turn-On Rise Time at $I_D = 0.5 \text{ A}, V_{DD} = 20 \text{ V}, V_{GS} = 10 \text{ V}, R_G = 24 \Omega$	$t_r$	-	5	-	ns
Turn-Off Delay Time at $I_D = 0.5 \text{ A}, V_{DD} = 20 \text{ V}, V_{GS} = 10 \text{ V}, R_G = 24 \Omega$	$t_{d(off)}$	-	6	-	ns
Turn-Off Fall Time at $I_D = 0.5 \text{ A}, V_{DD} = 20 \text{ V}, V_{GS} = 10 \text{ V}, R_G = 24 \Omega$	$t_f$	-	23	-	ns
<b>Body-Diode PARAMETERS</b>					
Body Diode Voltage at $I_S = 300 \text{ mA}$	$V_{SD}$	-	-	1.2	V
Body-Diode Continuous Current	$I_S$	-	-	500	mA



## Electrical Characteristics Curves

Fig. 1 Typical Output Characteristics

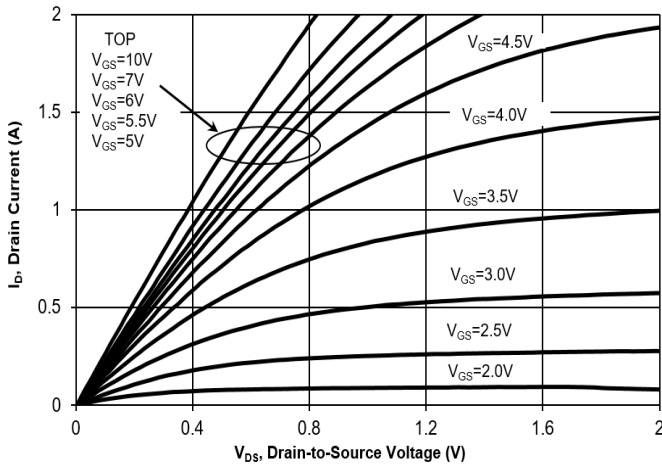


Fig. 2 Typical Transfer Characteristics

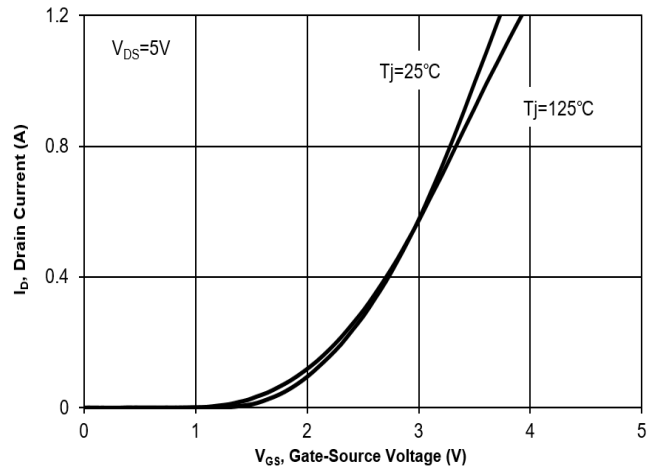


Fig. 3 On-Resistance vs. Drain Current

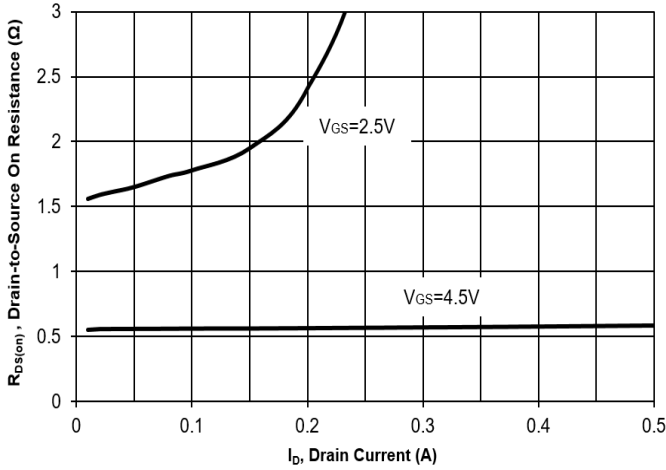


Fig. 4 On-Resistance vs. Gate-Source Voltage

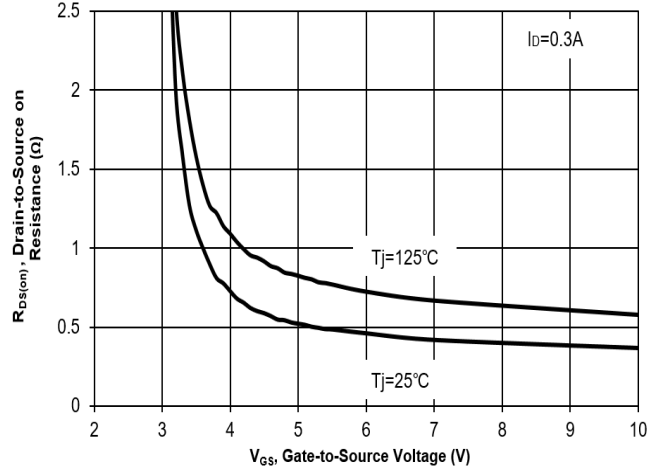


Fig. 5 On-Resistance vs. Tj

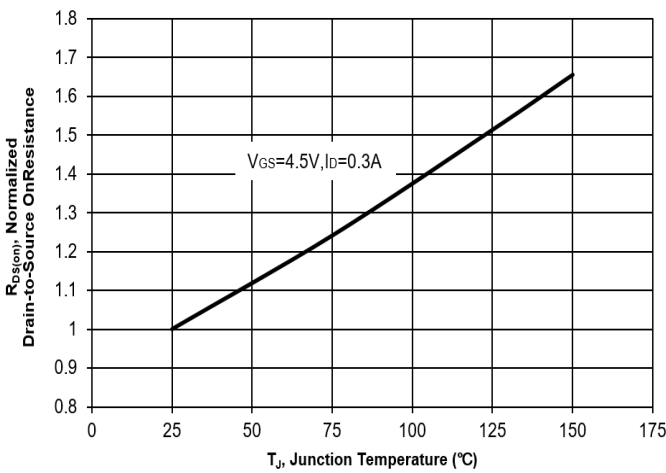
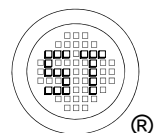
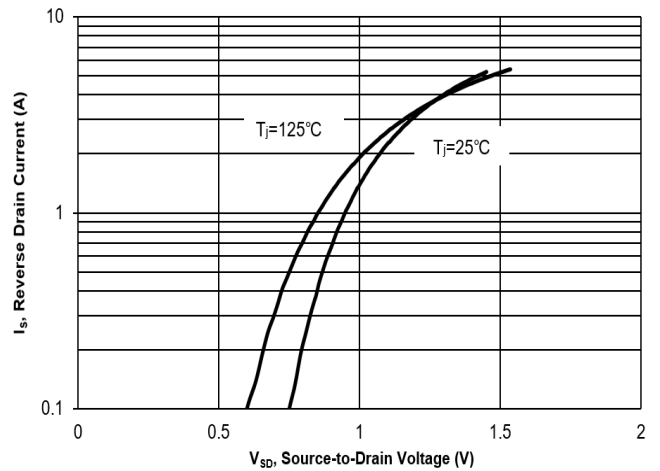


Fig. 6 Typical Body-Diode Forward Characteristics



## Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

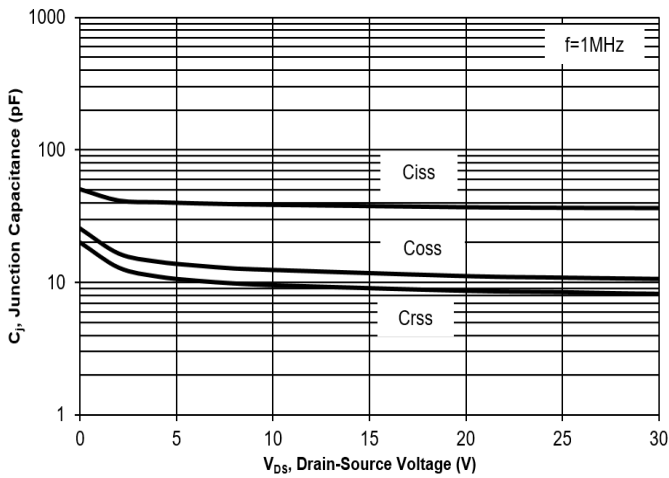


Fig. 8 Drain-Source Leakage Current vs.  $T_j$

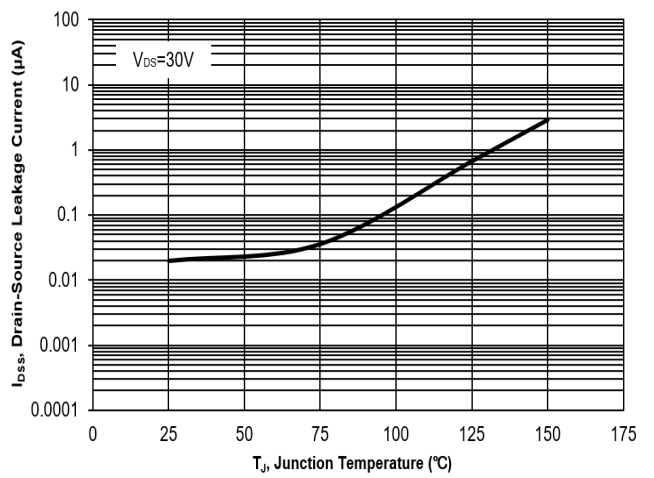


Fig. 9  $V_{(BR)DSS}$  vs. Junction Temperature

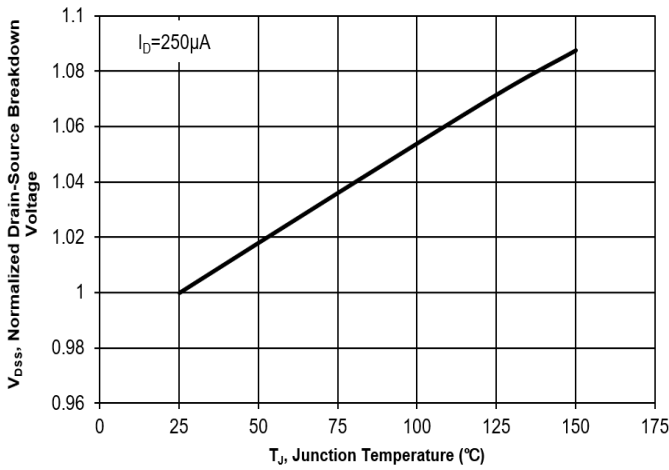


Fig. 10 Gate Threshold Variation vs.  $T_j$

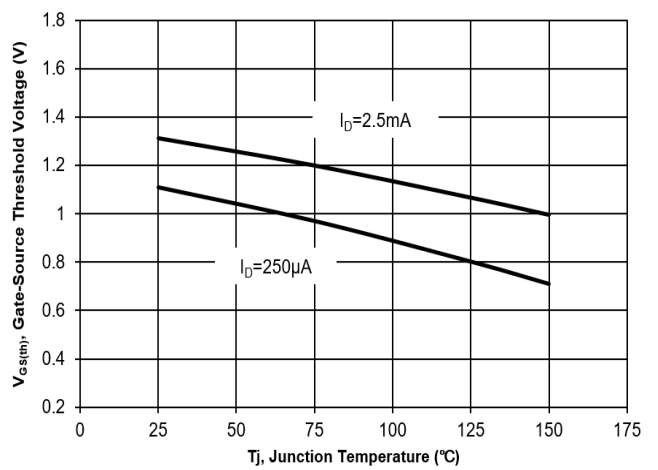
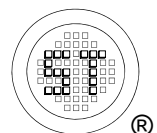
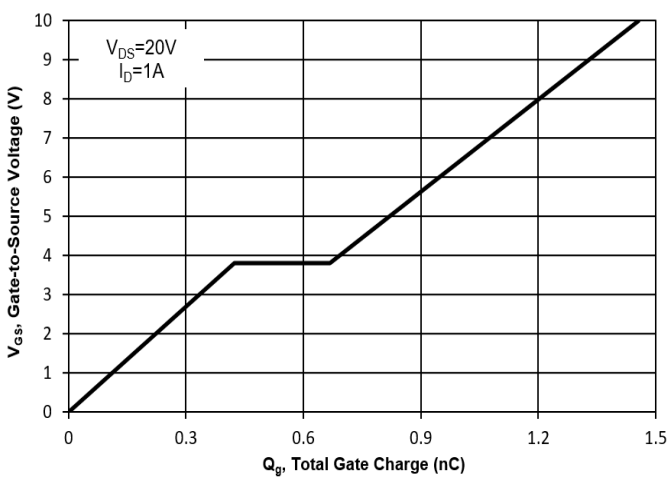


Fig. 11 Gate Charge



## Test Circuits

Fig.1-1 Switching times test circuit

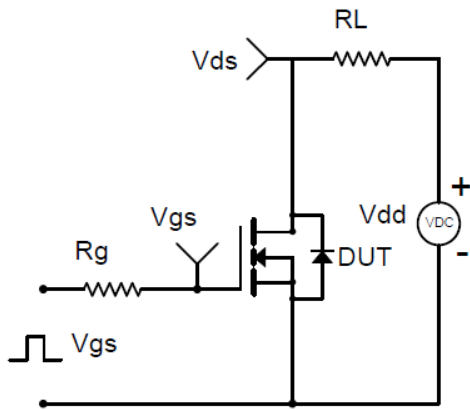


Fig.1-2 Switching Waveform

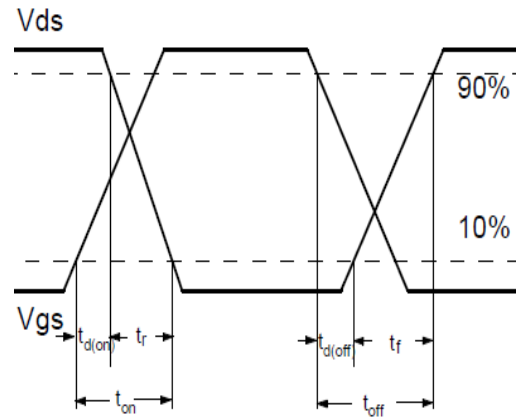


Fig.2-1 Gate charge test circuit

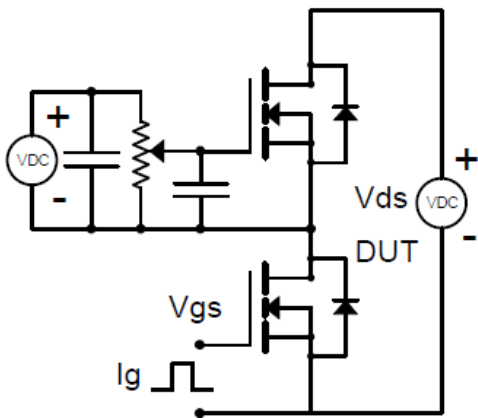
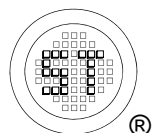
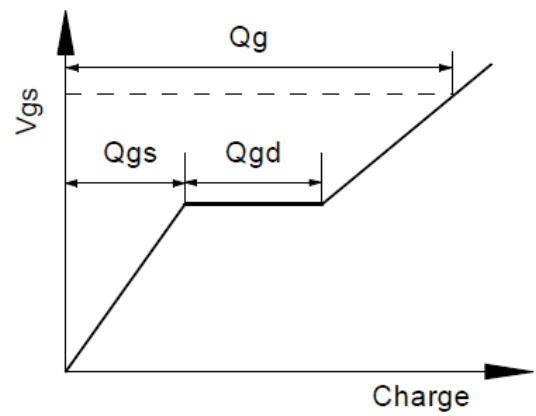


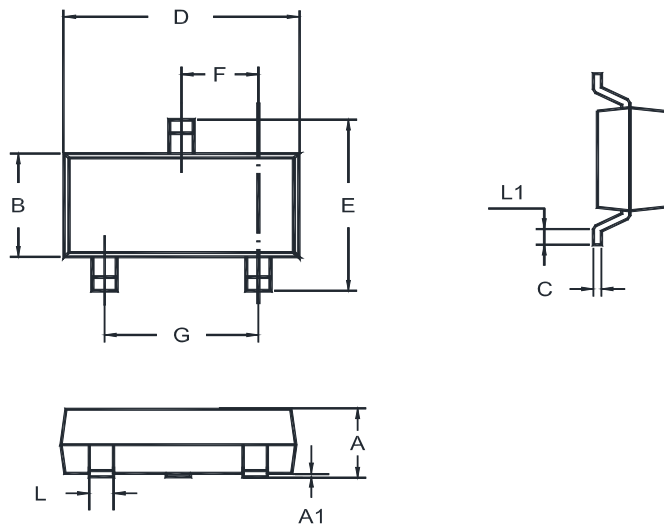
Fig.2-2 Gate charge waveform



# MMFTN4003K

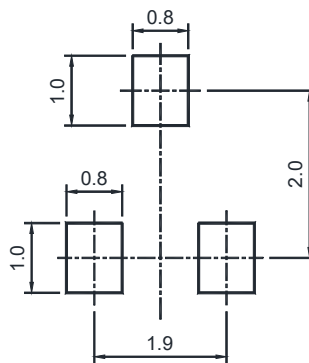
## Package Outline (Dimensions in mm)

SOT-23



Unit	A	A1	B	C	D	E	F	G	L	L1
mm	1.20	0.100	1.40	0.19	3.04	2.6	1.02	2.04	0.51	0.2
	0.89	0.013	1.20	0.08	2.80	2.2	0.89	1.78	0.37	MIN

## Recommended Soldering Footprint



## Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-23	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

## Marking information

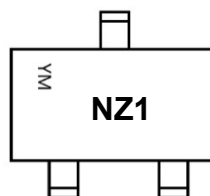
" NZ1 " = Part No.

" YM " = Date Code Marking

" Y " = Year

" M " = Month

Font type: Arial



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